

RULE 63 (37 C.F.R. 1.63)
INVENTORS DECLARATION FOR PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

As a below named inventor, I hereby declare that my residence, mailing address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF, AND ELECTRONIC DEVICE.

the specification of which (check applicable box(es)):

☐ is attached hereto

☐ was filed on

as U.S. Application Serial No.

(Atty. Dkt. No. -)

☒ was filed as PCT International application No.

PCT/JP2004/008322

on

June 14, 2004

and (if applicable to U.S. or PCT application) was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed or, if no priority is claimed, before the filing date of this application:

Priority Foreign Application(s):

Application Number

Country

Day/Month/Year Filed

2003-177272

Japan

June 20, 2003

2004-079273

Japan

March 18, 2004

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below.

Application Number

Date/Month/Year Filed

I hereby claim the benefit under 35 U.S.C. 120/365 of all prior United States and PCT international applications listed above or below:

Prior U.S./PCT Application(s):

Application Serial No.

Day/Month/Year Filed

Status: patented
pending, abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. And on behalf of the owner(s) hereof, I hereby appoint Nixon & Vanderhye P.C., telephone number

703-816-4000 (to whom all communications are to be directed) and the attorneys of: **Customer Number 23117**, individually and collectively owner's/owners' attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent. I also authorize Nixon & Vanderhye to add or delete attorneys from that Customer Number, and to act and rely solely on instructions directly communicated from the person, assignee, attorney, firm, or other organization sending instructions to Nixon & Vanderhye on behalf of the owner(s).

1. Inventor's Signature: Toshinori Sugihara Date: 12/9/2005
Inventor: Toshinori SUGIHARA Japanese
(first) MI (last) (citizenship)
Residence: (city) Kameyama-shi (state/country) Mie Japan
Mailing Address: 1888-6-1-408, Tamura-cho Kameyama-shi Mie Japan
(Zip Code) 519-0213

2. Inventor's Signature: _____ Date: _____
Inventor: Hideo OHNO Japanese
(first) MI (last) (citizenship)
Residence: (city) Sendai-shi (state/country) Miyagi Japan
Mailing Address: 3-33-10, Katsura Izumi-ku Sendai-shi Miyagi Japan
(Zip Code) 981-3134

[X] See attached sheet(s) for additional inventor(s) information!!

Serial No.
Page 2

3.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	Masashi (first)	MI	KAWASAKI (last)	Japanese (citizenship)	Date: _____
4.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
5.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
6.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
7.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
8.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
9.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
10.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
11.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____
12.	Inventor's Signature: _____ Inventor: _____ Residence: (city) _____ Mailing Address: _____ (Zip Code) _____	(first)	MI	(last)	(citizenship)	Date: _____

FOR ADDITIONAL INVENTORS, check box ☐ and attach sheet with same information and signature and date for each.

RULE 63 (37 C.F.R. 1.63)
INVENTORS DECLARATION FOR PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

As a below named inventor, I hereby declare that my residence, mailing address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF, AND ELECTRONIC DEVICE

the specification of which (check applicable box(es)):

☐ is attached hereto
☐ was filed on _____ as U.S. Application Serial No. _____ (Atty. Dkt. No. -)
☒ was filed as PCT International application No. PCT/JP2004/008322 on June 14, 2004
and (if applicable to U.S. or PCT application) was amended on _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed or, if no priority is claimed, before the filing date of this application:

Priority Foreign Application(s):

Application Number	Country	Day/Month/Year Filed
2003-177272	Japan	June 20, 2003
2004-079273	Japan	March 18, 2004

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below.

Application Number	Date/Month/Year Filed
--------------------	-----------------------

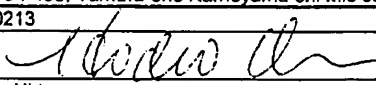
I hereby claim the benefit under 35 U.S.C. 120/365 of all prior United States and PCT international applications listed above or below:

Prior U.S./PCT Application(s):

Application Serial No.	Day/Month/Year Filed	Status: patented pending, abandoned
------------------------	----------------------	--

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. And on behalf of the owner(s) hereof, I hereby appoint Nixon & Vanderhye P.C., telephone number 703-816-4000 (to whom all communications are to be directed) and the attorneys of: **Customer Number 23117**, individually and collectively owner's/owners' attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent. I also authorize Nixon & Vanderhye to add or delete attorneys from that Customer Number, and to act and rely solely on instructions directly communicated from the person, assignee, attorney, firm, or other organization sending instructions to Nixon & Vanderhye on behalf of the owner(s).

1. Inventor's Signature: _____ Date: _____
Inventor: Toshinori (first) MI SUGIHARA (last) Japanese (citizenship)
Residence: (city) Kameyama-shi (state/country) Mie Japan
Mailing Address: 1888-6-1-408, Tamura-cho Kameyama-shi Mie Japan
(Zip Code) 519-0213

2. Inventor's Signature:  Date: Dec. 8, 2004
Inventor: Hideo (first) MI OHNO (last) Japanese (citizenship)
Residence: (city) Sendai-shi (state/country) Miyagi Japan
Mailing Address: 3-33-10, Katsura Izumi-ku Sendai-shi Miyagi Japan
(Zip Code) 981-3134

[X] See attached sheet(s) for additional inventor(s) information!!

3.	Inventor's Signature: _____	Date: _____
	Inventor: Masashi (first) MI KAWASAKI (last) Japanese (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: 35-1-101, Kawauchimotohasekura Aoba-ku Sendai-shi Miyagi Japan	
	(Zip Code) 980-0861	
4.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
5.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
6.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
7.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
8.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
9.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
10.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
11.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
12.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) MI _____ (last) _____ (citizenship)	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	

FOR ADDITIONAL INVENTORS, check box [] and attach sheet with same information and signature and date for each.

RULE 63 (37 C.F.R. 1.63)
INVENTORS DECLARATION FOR PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

As a below named inventor, I hereby declare that my residence, mailing address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF, AND ELECTRONIC DEVICE

the specification of which (check applicable box(s)):

☐ is attached hereto
☐ was filed on _____ as U.S. Application Serial No. _____ (Atty. Dkt. No. -)
☒ was filed as PCT International application No. PCT/JP2004/008322 on June 14, 2004
and (if applicable to U.S. or PCT application) was amended on _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose to the Patent Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed or, if no priority is claimed, before the filing date of this application:

Priority Foreign Application(s):

Application Number	Country	Day/Month/Year Filed
2003-177272	Japan	June 20, 2003
2004-079273	Japan	March 18, 2004

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below.

Application Number	Date/Month/Year Filed
--------------------	-----------------------

I hereby claim the benefit under 35 U.S.C. 120/365 of all prior United States and PCT international applications listed above or below:

Prior U.S./PCT Application(s):


Application Serial No.	Day/Month/Year Filed	Status: patented pending, abandoned
------------------------	----------------------	--

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. And on behalf of the owner(s) hereof, I hereby appoint Nixon & Vanderhye P.C., telephone number

703-816-4000 (to whom all communications are to be directed) and the attorneys of: **Customer Number 23117**, individually and collectively owners' owners' attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent. I also authorize Nixon & Vanderhye to add or delete attorneys from that Customer Number, and to act and rely solely on instructions directly communicated from the person, assignee, attorney, firm, or other organization sending instructions to Nixon & Vanderhye on behalf of the owner(s).

1.	Inventor's Signature: _____	Date: _____
	Inventor: Toshinori (first) MI SUGIHARA (last) Japanese (citizenship)	
	Residence: (city) Kameyama-shi (state/country) Mie Japan	
	Mailing Address: 1888-6-1-408, Tamura-cho Kameyama-shi Mie Japan	
	(Zip Code) 519-0213	
2.	Inventor's Signature: _____	Date: _____
	Inventor: Hideo (first) MI OHNO (last) Japanese (citizenship)	
	Residence: (city) Sendai-shi (state/country) Miyagi Japan	
	Mailing Address: 3-33-10, Katsura Izumi-ku Sendai-shi Miyagi Japan	
	(Zip Code) 981-3134	

[X] See attached sheet(s) for additional inventor(s) information!!

3.	Inventor's Signature: 	Date: <u>Dec. 12, 2005</u>
	Inventor: <u>Masashi</u> <u>MI</u> <u>KAWASAKI</u> (first) (last)	<u>Japanese</u> (citizenship)
	Residence: (city) _____ (state/country) _____	
	Mailing Address: <u>35-1-101, Kawauchimotohasekura Aoba-ku Sendai-shi Miyagi Japan</u>	
	(Zip Code) <u>980-0861</u>	
4.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
5.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
6.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
7.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
8.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
9.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
10.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
11.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	
12.	Inventor's Signature: _____	Date: _____
	Inventor: _____ (first) _____ MI _____ (last) _____ (citizenship) _____	
	Residence: (city) _____ (state/country) _____	
	Mailing Address: _____	
	(Zip Code) _____	

FOR ADDITIONAL INVENTORS, check box [] and attach sheet with same information and signature and date for each.